EPO-TEK® H70E-175

Epoxy; Epoxide

Epoxy Technology Inc.

Message:

EPO-TEK® H70E-175 is a two component, thermally conductive, electrically insulating epoxy adhesive for semiconductor, microelectronic and opto-electronic packaging. It may be used in aluminum heat sinking power devices in the form of hybrid circuits or at the SMD/PCB level.

| General Information | | | | |
|---|------------------------------------|----------|-----|--|
| Features | Electrically Insulating | | | |
| | Thermally Conductive | | | |
| Uses | Adhesives | | | |
| | Electrical/Electronic Applications | | | |
| | Military Applications | | | |
| | Optical Applications | | | |
| | Printed Circuit Boards | | | |
| Agency Ratings | EC 1907/2006 (REACH) | | | |
| | EU 2003/11/EC | | | |
| | EU 2006/122/EC | | | |
| RoHS Compliance | RoHS Compliant | | | |
| Forms | Paste | | | |
| Physical | Nominal Value | Unit | | |
| Particle Size | < 20.0 | μm | | |
| Degradation Temperature | 392 | °C | TGA | |
| Die Shear Strength - >4 kg (23°C) | 9.38 | МРа | | |
| Operating Temperature | | | | |
| Continuous | -55 to 200 | °C | | |
| Intermittent | -55 to 300 | °C | | |
| Storage Modulus (23°C) | 5.22 | GPa | | |
| Thixotropic Index | 2.55 | | | |
| Weight Loss on Heating | | | | |
| 200°C | 0.59 | % | | |
| 250°C | 1.4 | % | | |
| 300°C | 3.3 | % | | |
| Thermal | Nominal Value | Unit | | |
| Glass Transition Temperature ¹ | > 70.0 | °C | | |
| CLTE - Flow | | | | |
| 2 | 2.6E-5 | cm/cm/°C | | |

| 3 | 8.4E-5 | cm/cm/°C | |
|-------------------------------|--|----------|-------------|
| Thermal Conductivity | 0.32 | W/m/K | |
| Thermoset | Nominal Value | Unit | Test Method |
| Thermoset Components | | | |
| Part A | Mix Ratio by Weight: 1.0 | | |
| Part B | Mix Ratio by Weight: 1.0 | | |
| Shelf Life (23°C) | 52 | wk | |
| Uncured Properties | Nominal Value | Unit | Test Method |
| Color | | | |
| ⁴ | Grey | | |
| 5 | Grey | | |
| Density | | | |
| Part A | 1.36 | g/cm³ | |
| Part B | 1.92 | g/cm³ | |
| Viscosity ⁶ (23°C) | 5.0 to 11 | Pa·s | |
| Curing Time (180°C) | 1.0 | hr | |
| Pot Life | 2900 | min | |
| Cured Properties | Nominal Value | Unit | Test Method |
| Shore Hardness (Shore D) | 88 | | |
| Lap Shear Strength (23°C) | > 13.8 | MPa | |
| Relative Permittivity (1 kHz) | 4.72 | | |
| Volume Resistivity (23°C) | 2.0E+13 | ohms·cm | |
| NOTE | | | |
| 1. | Dynamic Cure 20-200°C/ISO 25 Min; Ramp -10-200°C @ 20°C/Min | | |
| 2. | Below Tg | | |
| 3. | Above Tg | | |
| 4. | Part B | | |
| 5. | Part A | | |
| 6. | 20 rpm | | |
| | | | |

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